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gnod in the HE UNITED STATES PATENT AND TRADEMARK OFFICE In re Application of Group Art Unit: Examiner: Not Yet Assigned CHEN, Ling and CAO, Wei Application No.: 10/050,654 INFORMATION DISCLOSUR Filing Date: January 16, 2002 **STATEMENT** CERTIFICATE OF MAILING I hereby certify that the correspondence enclosed herein For: METHOD FOR GROWING THIN is being deposited as first class mail with the United States Postal Service on this date April 17, 2002, in an **FILMS BY CATALYTIC** envelope addressed to: Asst. Commissioner for Patents, **ENHANCEMENT** Washington, D.C. 20231.

**Box IDS** Asst. Commissioner for Patents Washington, D.C. 20231

Dear Sir:

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Applicant submits herewith patents, publications or other information (attached hereto and listed on the attached Form PTO-1449) of which he is aware, pursuant to his duty to disclose in accordance with 37 C.F.R. § 1.56.

This Information Disclosure Statement is filed before the mailing of the first Office Action on the merits as set forth in 37 C.F.R. § 1.97.

A list of the patent(s) or publication(s) is set forth on the attached Form PTO-1449 (Modified). A copy of each of the items listed on form PTO-1449 is supplied herewith.

A concise explanation of relevance of the items listed on PTO-1449 is not given. The Examiner is reminded that a "concise explanation of the relevance" of the submitted prior art "may be nothing more than identification of the particular figure or paragraph of the patent or publication which has some relation to the claimed invention," MPEP § 609.

While the information and references disclosed in this Information Disclosure Statement may be "material" pursuant to 37 C.F.R. § 1.56, it is not intended to constitute an admission that any patent, publication or other information referred to therein is "prior art" for this invention unless specifically designated as such.

In accordance with 37 C.F.R. § 1.97(g), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 C.F.R. § 1.56(a) exists. Furthermore, pursuant to 37 C.F.R. § 1.97(h), the filing of this Information Disclosure Statement shall not be construed to be an admission that the information cited in this statement is, or is considered to be, material to patentability, as defined in 1.56(b). It is submitted that the Information Disclosure Statement is in compliance with 37 C.F.R. § 1.98 and MPEP § 609 and the Examiner is respectfully requested to consider the listed references.

The Commissioner is hereby authorized to charge any additional fees or credit overpayment to our Deposit Account No. 04-0822.

Respectfully submitted,

**DERGOSITS & NOAH LLP** 

Dated: April 17, 2002

By:

Donald R. McKenna Reg. No. 44,922

DERGOSITS & NOAH LLP Four Embarcadero Center, Suite 1450 San Francisco, California 94111 (415)705-6377

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(Rev. 7-80)	Patent and DANELA	PY	422.05	10/050,654
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LIST OF REFERENCES CIT	ED BY APPLICANT	Applicant:		()
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